AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A wiring board comprising:

a conductor layer comprising Fe and Cu; and

at least one of a radiator, a connection terminal, a cover and a circuit component selected from the group consisting of a semiconductor element, a condenser, an inductor and a resistor, connected to the conductor layer through a joining member comprising a brazing material,

which wiring board is obtained by coating a copper paste comprising a copper powder, an organic vehicle and an Fe_2O_3 particle mainly comprising Fe_2O_3 as a conductor layer on a ceramic green sheet, and simultaneously firing the ceramic green sheet and coated copper paste.

2. (original): The wiring board according to claim 1, wherein a surface of the conductor layer is subjected to a plating treatment.

3. (canceled).

4. (previously presented): The wiring board according to claim 1, wherein the copper paste comprises more than 20 parts by mass of the organic vehicle per 100 parts by mass of the copper powder.

5. (currently amended): The wiring board according to claim 1, wherein the copper paste comprises a ceramic particle having an average particle size of 100 nm or less selected

from the group consisting of ~~glass forming oxides,~~ oxides of alkali metals and alkaline earth metals, Al_2O_3, TiO_2, CeO_2 and mullite.

6. (previously presented): The wiring board according to claim 1, which is obtained by a method comprising the steps of

coating the copper paste on a ceramic green sheet;

exposing the coated sheet to a wet nitrogen atmosphere at 650 to 900°C so as to remove organic components; and

simultaneously firing the ceramic green sheet and coated copper paste at 850 to 1,050°C after the exposing.

7. (currently amended): A copper paste comprising a copper powder, an organic vehicle ~~and~~, an Fe2O3 particle mainly comprising Fe2O3, and

which comprises a ceramic particle having an average particle size of 100 nm or less selected from the group consisting of oxides of alkali metals and alkaline earth metals, Al_2O_3, TiO_2, CeO_2 and mullite.

8. (original): The copper paste according to claim 7, wherein the copper paste comprises more than 20 parts by mass of the organic vehicle per 100 parts by mass of the copper powder.

9. (canceled).

10. (previously presented): The wiring board according to claim 1, wherein said Fe2O3 particle has an average particle size of 1 μm or less.

11. (previously presented): The copper paste according to claim 7, wherein said Fe2O3 particle has an average particle size of 1 μm or less.

12. (new): The wiring board according to claim 5, wherein the ceramic particle having an average particle size of 100 nm or less has a hydrophilic surface.

13. (new): The copper paste according to claim 7, wherein the ceramic particle having an average particle size of 100 nm or less has a hydrophilic surface.

14. (new): The wiring board according to claim 5, wherein the ceramic particle having an average particle size of 100 nm or less comprises TiO_2.

15. (new): The copper paste according to claim 7, wherein the ceramic particle having an average particle size of 100 nm or less comprises TiO_2.